

PATENT ABSTRACTS OF JAPAN

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(21)Application number : 10-193821

(71)Applicant : THREE BOND CO LTD

(22)Date of filing : 09.07.1998

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(54) THERMOSETTING ELECTROCONDUCTIVE ADHESIVE

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a thermosetting electroconductive adhesive improved in storage stability, which adhesive contains a product prepared by subjecting to a specified pretreatment a curing agent prepared by pretreating with an isocyanate the reaction product of an imidazole derivative with an epoxy compound.

SOLUTION: There is provided a thermosetting electroconductive adhesive comprising a curing agent prepared by pretreating with an isocyanate the reaction product of an imidazole derivative with an epoxy compound, an epoxy composition curable with the curing agent, and an electroconductive material, wherein the curing agent is further treated with an isocyanate compound and a polyol compound in an epoxy resin which does not dissolve or swell the curing agent. In an embodiment, the pretreatment with the isocyanate compound and the polyol compound is carried out by using 100 pts.wt. curing agent, 0.01-20 pts.wt. isocyanate compound, and 0.01-20 pts.wt. polyol compound.

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isocyanato compound and a polyol compound in an epoxy resin not dissolving or swelling the curative.

USE - The thermosetting electroconductive adhesives are for adhering counter wiring patterns by thermal contact bonding on electronic parts assembly.

ADVANTAGE - The thermosetting electroconductive adhesives have much improved storage stability, excellent solvent resistance and thermal and physical stability without foam mixing and fall in glass transition temperature even with use of a polyol compound.

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Title Terms: THERMOSETTING; ELECTROCONDUCTING; ADHESIVE; IMPROVE; STORAGE; STABILISED; COMPRISE; CURE; OBTAIN; TREAT; REACT; PRODUCT; IMIDAZOLE; DERIVATIVE; EPOXY; COMPOUND; ISOCYANATE

Derwent Class: A21; A25; A81; G03; L03

International Patent Class (Main): C09J-009/02; C09J-163/00

International Patent Class (Additional): C08G-059/40; C09J-175/00

File Segment: CPI

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DIALOG(R)File 351:Derwent WPI

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Thermosetting electroconductive adhesives with improved storage stability
- comprising a curative obtained by treating a reaction product of an
imidazole derivative and an epoxy compound with an isocyanate

Patent Assignee: TOKYO THREE BOND CO LTD (TOKT)

Number of Countries: 001 Number of Patents: 002

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 2000026829	A	20000125	JP 98193821	A	19980709	200016 B
JP 3562323	B2	20040908	JP 98193821	A	19980709	200459

Priority Applications (No Type Date): JP 98193821 A 19980709

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
JP 2000026829	A		6	C09J-163/00	
JP 3562323	B2	10		C09J-009/02	Previous Publ. patent JP 2000026829

Abstract (Basic): JP 2000026829 A

NOVELTY - A thermosetting electroconductive adhesive comprises a
curative obtained by treating a reaction product of an imidazole
derivative and an epoxy compound with an isocyanate, an epoxy
composition to be cured with the curative and an electroconductive
material.

DETAILED DESCRIPTION - The curative is further treated with an
isocyanato compound and a polyol compound in an epoxy resin not
dissolving or swelling the curative.

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adhering countering wiring patterns by thermal contact bonding on
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